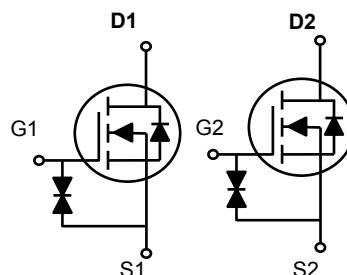


Main Product Characteristics

BV_{DSS}	30V
$R_{DS(ON)}$	450m Ω
I_D	600mA



SOT-563



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFJ03600 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current-Continuous ($T_A=25^{\circ}\text{C}$)	I_D	600	mA
Drain Current-Continuous ($T_A=70^{\circ}\text{C}$)		480	
Drain Current-Pulsed ¹	I_{DM}	2.4	A
Power Dissipation ($T_A=25^{\circ}\text{C}$)	P_D	313	mW
Power Dissipation-Derate above 25°C		2.5	mW/ $^{\circ}\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	400	$^{\circ}\text{C/W}$
Operating Junction Temperature Range	T_J	-55 To +150	$^{\circ}\text{C}$
Storage Temperature Range	T_{STG}	-55 To +150	$^{\circ}\text{C}$

Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On / Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	30	-	-	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V, T _J =25°C	-	-	1	μA
		V _{DS} =24V, V _{GS} =0V, T _J =125°C	-	-	10	μA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±12V, V _{DS} =0V	-	-	±20	μA
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =0.3A	-	370	450	mΩ
		V _{GS} =2.5V, I _D =0.2A	-	510	650	
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =250uA	0.5	0.7	1.2	V
Forward Transconductance	g _{fs}	V _{DS} =4V, I _D =0.3A	-	0.8	-	S
Dynamic and Switching Characteristics						
Total Gate Charge ^{2,3}	Q _g	V _{DS} =15V, I _D =0.3A V _{GS} =4.5V	-	2.6	5.2	nC
Gate-Source Charge ^{2,3}	Q _{gs}		-	0.9	1.8	
Gate-Drain Charge ^{2,3}	Q _{gd}		-	0.6	1.2	
Turn-On Delay Time ^{2,3}	t _{d(on)}	V _{DD} =15V, R _G =10Ω V _{GS} =4.5V, I _D =0.3A	-	5.5	11	nS
Rise Time ^{2,3}	t _r		-	4	8	
Turn-Off Delay Time ^{2,3}	t _{d(off)}		-	14.5	29	
Fall Time ^{2,3}	t _f		-	6.5	13	
Input Capacitance	C _{iss}	V _{DS} =15V, V _{GS} =0V, F=1MHz	-	43	65	pF
Output Capacitance	C _{oss}		-	16	25	
Reverse Transfer Capacitance	C _{rss}		-	8.5	15	
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current	I _S	V _G =V _D =0V, Force Current	-	-	0.6	A
Pulsed Source Current	I _{SM}		-	-	1.2	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =0.3A, T _J =25°C	-	-	1	V

Note:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2. Pulse test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristic Curves

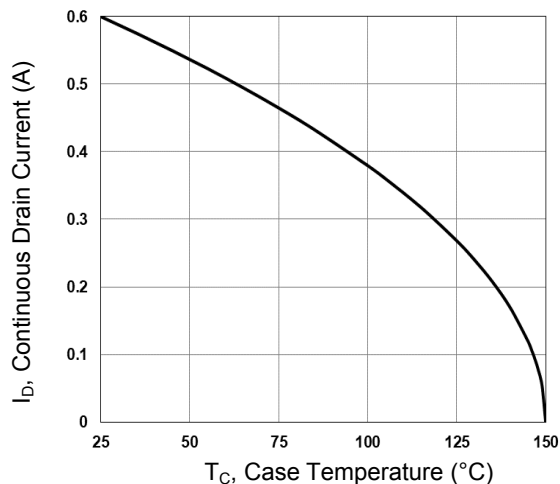


Figure 1. Continuous Drain Current vs. T_C

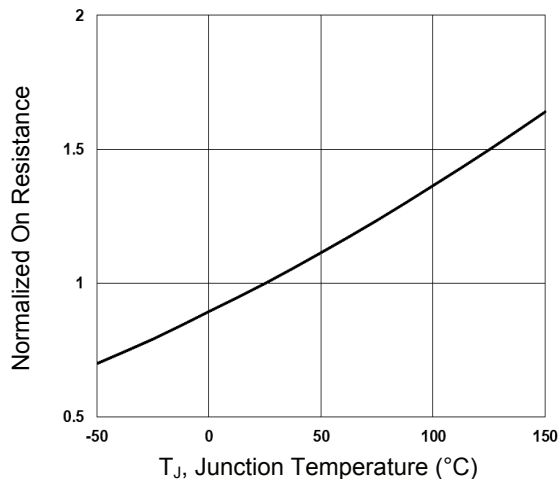


Figure 2. Normalized $R_{DS(on)}$ vs. T_J

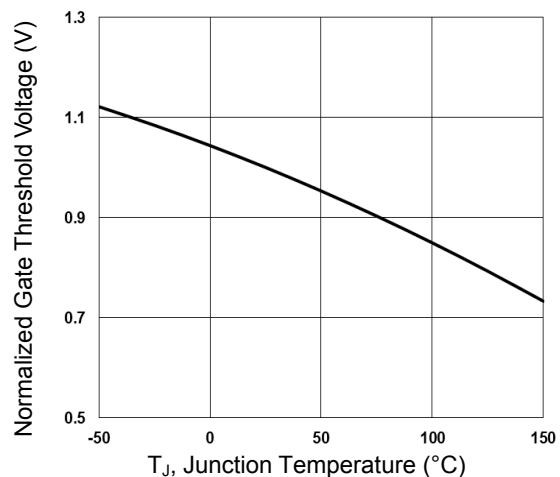


Figure 3. Normalized V_{th} vs. T_J

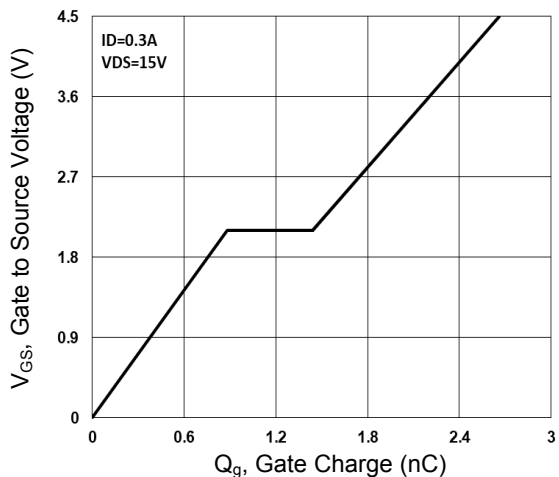


Figure 4. Gate Charge Characteristics

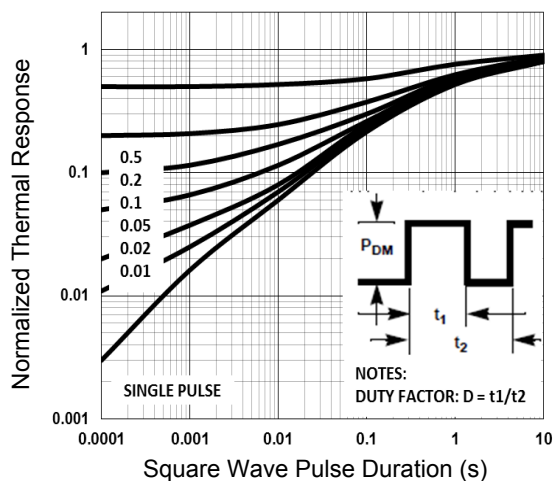


Figure 5. Normalized Transient Impedance

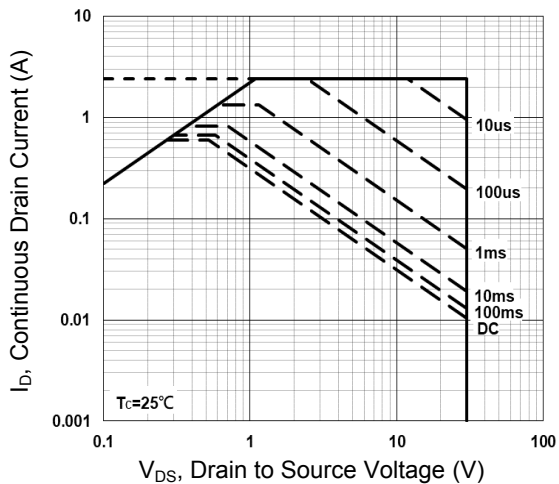
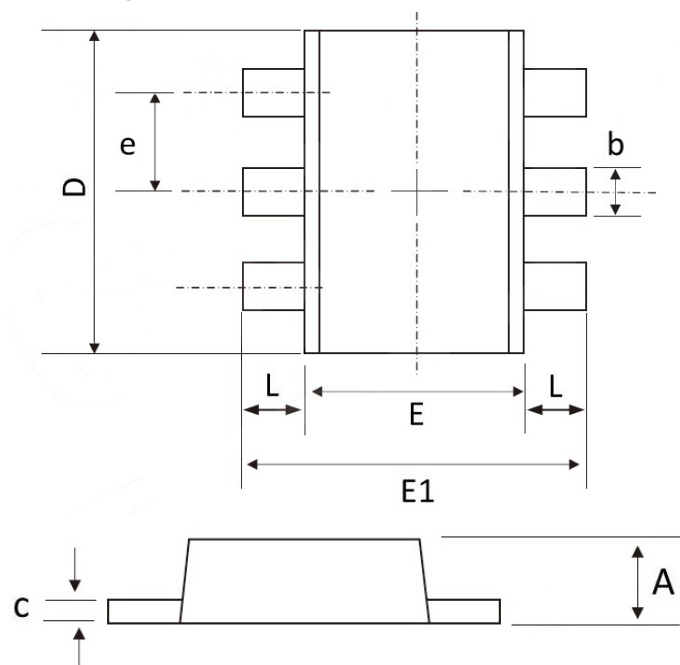


Figure 6. Maximum Safe Operation Area

Package Outline Dimensions (SOT-563)



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Max	Min	Max	Min
A	0.600	0.500	0.024	0.020
b	0.300	0.150	0.012	0.006
c	0.180	0.100	0.007	0.004
D	1.700	1.500	0.067	0.059
E	1.250	1.100	0.049	0.043
E1	1.700	1.550	0.067	0.061
e	0.500 BSC		0.020 BSC	
L	0.300	0.100	0.012	0.004